ON Semiconductor®

Final Product/Process Change Notification

Document #:FPCN23931Y
Issue Date: 12 May 2021

Title of Change:	Change of assembly and test site, lead frame design and mold compound for MicroFC-30020 and MicroFC-30050
Proposed First Ship date:	19 Aug 2021 or earlier if approved by customer
Contact Information:	Contact your local ON Semiconductor Sales Office or Deborah.Herbert@onsemi.com
PCN Samples Contact:	Contact your local ON Semiconductor Sales Office or <PCN.samples@onsemi.com>. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or Ricky.Garcia@onsemi.com
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com
Marking of Parts/ Traceability of Change:	No OPN change. No marking, but visible leadframe change. Traceability will be via Assembly Lot date code.
Change Category:	Assembly Change
Change Sub-Category(s):	Manufacturing Site Transfer, Material Change

Sites Affected:

ON Semiconductor Sites	External Foundry/Subcon Sites
None	Site A Site B

Description and Purpose:

	Before Change Description (Site A)	After Change Description (Site B)
Leadframe	Refer to image and description below	Refer to image and description below
Mold compound	NITTO NT-332H Clear CPD	NITTO NT-8524H Clear CPD

Leadframe change description:
No base material change as a result of this change.

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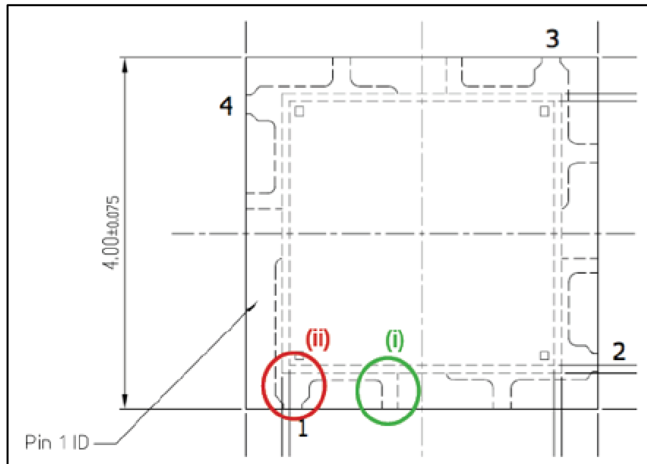
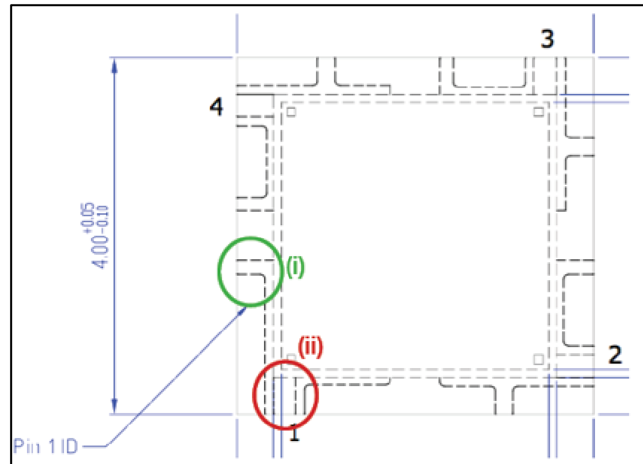
BEFORE



AFTER



(i) The half-etch tab on pin 1 is relocated - the half etch tabs do not contact the base of the package as there is package material underneath so there is no change to the package footprint and the recommended solder footprint has not changed.
(ii) The pull in etch of the solder pads 1 - 4 at the edge of the package have been changed to a flat edge. There is no change to the recommended solder footprint.

The full POD documents can be accessed as follows:
Before:
https://www.onsemi.com/pub/collateral/512ah.pdf

After:
https://www.onsemi.com/pub/collateral/512af.pdf

There is no product marking change as a result of this change.

Sample Availability:
Samples will be available at the end of May 2021

Qualification Plan:

QV DEVICE NAME : MicroFC-30035-SMT
RMS : N/A
PACKAGE : CWDFN-4 4x4

Parts are qualified by similarity to MicroFC-30035-SMT product which is already complete. Qualification of MicroFC-30035-SMT included MSL3 preconditioning, 3 x solder reflow, UHAST (110°C, 85%RH), temperature cycling (-40°C – 85°C), HTS (504HRS, 125°C).

List of Affected Parts:

Note: *Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the* ***PCN Customized Portal.***

Part Number	Qualification Vehicle
MICROFC-30050-SMT-TR1	NA
MICROFC-30050-SMT-TR	NA
MICROFC-30020-SMT-TR1	NA
MICROFC-30020-SMT-TR	NA